

Data requirements for semiconductor die —

**Part 6-1: Exchange data formats and
data dictionary — Data exchange —
DDX file format**

ICS 31.080.01

National foreword

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the ES title page, pages 2 to 36 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

This British Standard, having been prepared under the direction of the Electrotechnical Sector Committee, was published under the authority of the Electrotechnical Standards Committee and comes into effect on 15 December 1999

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